FOR ADDITIONAL INFORMATION CONTACT:
Phone: (518) 452-2880
E-mail: info@yincae.com

YINCAE Advanced Materials, LLC
19 Walker Way, Albany, NY 12205
(518) 452-2880
www.yincae.com

FOR IMMEDIATE RELEASE

Press Release

YINCAE Launches Diamond Underfill UF 158D with 8 W/m·K Thermal Conductivity

09/23/2025 (Albany, NY) – YINCAE, a leader in advanced electronic materials, has introduced **Diamond Underfill UF 158D**, delivering **8 W/m·K thermal conductivity**—a new standard in heat dissipation for advanced semiconductor packaging.

Built with **nano-engineered diamond particles**, UF 158D combines high thermal performance with excellent mechanical reliability, low CTE mismatch, and strong adhesion. It is optimized for **flip-chip, 2.5D/3D packaging, and high-density interconnects**, reducing solder fatigue and extending device lifetime.

“UF 158D enables customers to push semiconductor performance further without sacrificing reliability,” said **Dr. Wusheng Yin, CEO of YINCAE**.

The product is available in both **dispensable and jettable formulations** and has passed **JEDEC reliability testing**.YINCAE will showcase **UF 158D** at **IMAPS 2025** in San Diego from September 30 to October 1 at **Booth #817**, and at **SMTAI 2025** in Chicago from October 21 to 23 at **Booth #2551**.

For more information on YINCAE’s UF 158D underfill, or to learn more about the YINCAE product range, please email us at: info@yincae.com. You can also find more information by visiting our website at: www.yincae.com

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Founded in 2005 & headquartered in Albany, New York, YINCAE Advanced Materials is a leading manufacturer and supplier of high-performance coatings, adhesives and electronic materials used in the microchip & optoelectronic devices. YINCAE products provide new technologies to support manufacturing processes from wafer level, to package level, to board level and final devices while facilitating smarter and faster production and supporting green initiatives.

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